

Fifty Years of Physics of Failure

Kaushik Chatterjee, Mohammad Modarres, Joseph B. Bernstein^{*}, and A. Christou

Center for Risk and Reliability

Department of Mechanical Engineering

University of Maryland College Park

This year marks the fiftieth anniversary since Physics of Failure (PoF) was first formally conceptualized in the first of a series of symposia in 1962 organized by the Rome Air Development Center (RADC)¹ of the US Air Force. The major driving force that established this approach to reliability had its roots in the 1940s and 1950s due to concerns in US military establishments about the reliability of electronic systems. According to *Mclinn* (2011), “By the 1940s reliability and reliability engineering still did not exist.” At the start of the World War II, it was discovered that over 50% of the airborne electronics equipment in storage was unable to meet the requirements of the Air Core and Navy (*Mclinn, 2011*). Much of the reliability work during that period had to do with fatigue and fracture of metals. For example, in 1945 a paper titled “Cumulative Damage in Fatigue” was published in the *Journal of Applied Mechanics* (*Miner, 1945*) in which expended life of metals were empirically modeled. In 1948, another paper titled “Statistical Aspects of Fracture Problems” was published in the *Journal of Applied Physics* (*Epstein, 1948*) in which the statistical foundation for the assessment of the life of materials was discussed. Then in 1950, the US military initiated an Ad Hoc group on reliability

¹ Now known as the Rome Laboratory.

* Current affiliation is Bar Ilan University, Ramat Gan, Israel.

of electronic equipment, which stated that for improving part reliability it is essential to develop better parts, establish quantitative reliability requirements for parts, and collect field failure data to determine the root cause of problems (*Ebel, 1998*). Several conferences began in the 1950s to focus on various reliability topics. One conference that warrants special mention is the Holm Conference on Electrical Contacts, which was started in 1955 emphasizing reliability physics. This conference established itself over the years as the primary source of reliability physics information on connectors.

Between 1955 and 1963, Waloddi Weibull produced several publications related to fatigue and creep mechanisms and derived the Weibull distribution on the basis of the weakest link model of failures in materials. For example, in 1959 Weibull produced a report for the US Military titled “Statistical Evaluation of Data from Fatigue and Creep Rupture Tests: Fundamental Concepts and General Methods” (*Weibull, 1959*) in which methods for evaluating fatigue failure data were discussed. In 1961, Weibull published a book on materials and fatigue testing while working as a consultant for the US Air Force Materials Laboratory (*Weibull, 1961*).

Having exposed to the mechanistic-based life models developed to assess fatigue and fracture caused failures, in 1961 RADC introduced a PoF program to address the growing complexity of military equipment and consequently higher number of failures observed using the underlying failure mechanisms. In 1962, researchers from Bell Labs published a paper on “High Stress Aging to Failure of Semiconductor Devices” that justified using of the Kinetic Theory as a basis for assessment of temperature-induced aging of semiconductor devices, and proposed the Arrhenius model to estimate life (*Dodson & Howard, 1961*). Based on these developments, the RADC and Armour Research Foundation of Illinois Institute of Technology (now IIT Research

Institute) organized the first PoF symposium in electronics in 1962. This symposium led the groundwork for future research and development activities related to PoF by RADC and several other organizations. Numerous original papers and ideas introducing and explaining the PoF concepts and methods were presented in these symposia.

In one of the original PoF paper presented in the first PoF symposium, *Vaccaro (1962)* opined that PoF should seek to relate the fundamental physical and chemical behavior of materials (i.e., failure mechanisms) to reliability parameters. This approach is based on the principle that to eliminate the occurrence of failures, it is essential to eliminate their root causes, and to do that one must understand the physics of the underlying failure mechanisms involved. *Davis (1962)* described the need for identifying probable failure mechanisms by which components fail as a function of time, environmental and operating stresses, as well as developing mathematical models to represent these mechanisms in order to meet reliability requirements of components. Various companies and universities conducting research on failure mechanisms were active participants. These included Raytheon, Syracuse University, and Motorola. Although PoF was key to improving design and reliability of components, higher costs in terms of facilities and manpower was identified as the critical impediment for using PoF at that time (*Ryerson, 1962*). The various key elements of PoF approach such as, identification of failure mode, mechanism, and cause were defined for the first time in this symposium (*Zierdt, 1962; Earles & Eddins, 1962*). *Levinson and Pohl (1962)* stated that change in performance of a component or material with time occurs as a result of natural processes that can be described by well-known laws. A thorough analysis of these laws as applied to a device, and its operating environment, can yield a mathematical relation for the failure rate as a function of the stresses to which that the device would be subjected.

Due to the success of the first symposium in 1962, four PoF symposia were held in subsequent years (until 1966) with many more papers describing concepts related to PoF. For example, *Tamburrino* (1963) provided key points about the requirements of a reliability physics program, e.g., materials, measurement techniques, and failure mechanisms. The need for part vendors to be kept abreast of available knowledge and understanding in failure physics was identified. It was stated that any changes in pre-established part processing or fabrication can potentially be a key factor in inducing new failure mechanisms, and should be closely coordinated with reliability engineers. *Bretts, Kozol and Lampert* (1963) provided accelerated tests results for resistors, which they correlated with physical degradation models to estimate time to failure. PoF was identified as an essential step in planning accelerated tests as well as evaluating them.

In third PoF symposium, *Ingram* (1964) described performance characteristics and failure mechanisms of a device in probabilistic terms. He suggested, “Environmental and stress conditions applicable to the device, and its performance and strength characteristics, are expressed in the form of multidimensional probability distributions. By joint evaluation of these probability distributions, a quantitative estimate of the reliability of the device can be obtained.” *Beau* (1964) described methods for managing and assessing the role of the human elements in PoF. He described three classical causes of failure as: reliability limitation inherent in the design; reliability degradation caused by the factory process; and reliability degradation caused by the user. According to him, the factory operator, in form of poor workmanship or operator error, introduced the human element in reliability of devices. *Workman* (1964) described the failure analysis practices followed in Texas Instruments at that time, and the need for incorporating

information gained from failure analysis in new reliability test design, process control, and new device design.

Shiomi (1965) introduced a generalized cumulative degradation model for estimation and prediction of component life under successive different stress levels. *Partridge, Hall, and Hanley* (1965) described the need for qualification and engineering evaluations to select vendors who are capable of supplying reliable semiconductor parts. They further stated that qualification tests alone are insufficient to determine the ability of vendors, but production procurement data from screen and burn-in can provide sufficient vendor history. *Church and Roberts* (1965) presented different causes of failure of a component, such as due to accidental damage during manufacture, assembly, testing, storage, or failure in service due to operating conditions or failure of another component.

Thomas (1966) used basic concepts of dimensional analysis to make general examination of mathematical models, e.g., Eyring's equation. He opined that the concepts of signal, noise and dimensionless variable could be used to formulate mathematical models, physical laws, and probability distributions. *Schenck* (1966) presented two forms of progressive failure mechanisms of a commercial silicon diode, and studied them as a function of various stress and measurement variables. Several papers were also presented that proposed nondestructive inspection and screening procedures based on PoF which later formed the basis for prognosis and health management concepts. For example, *Gill and Workman* (1966) presented a reliability screening procedure (consisting of destructive tests and nondestructive inspections) based on identifying failure mechanisms resulting from high-stress tests and failure analysis. *Potter and Sawyer* (1966) presented an optical scanning-based nondestructive technique to study various

semiconductor device phenomena and identify causes of anomalous device behavior in order to improve device reliability.

From 1967 onwards, IEEE sponsored the “Reliability Physics Symposium (IRPS)” that continues even today presenting wide ranges of PoF related research. For example, *Ryerson* (1967) presented mathematical models for semiconductor diodes illustrating how failure mechanisms, part strengths, and application stresses interact and affect the failure rate of component parts. *Keen, Loewenstern, and Schnable* (1967) presented mechanisms of failure in ohmic and expanded contacts, including metal-semiconductor contacts and bonds to metallization in semiconductor devices. *Payne* (1967) presented a failure mechanism for barium titanate capacitors studying the PoF. *Frankel and Kinsolving* (1970) discussed the need of reliability testing of components for hostile environments, by first simulating field conditions and then developing accelerating laboratory conditions. *Hollingshead* (1970) introduced a technique for optimizing the selection of parts for system application by reliability and quality levels through systematizing the compilation and processing of necessary data. The comparative influence of performance parameters such as repair cost, storage time, and cost of failure were discussed. *Schwuttke* (1970) showed that peripheral yield loss in silicon wafers can be minimized whenever temperature gradients arising during cooling of a row of wafers are eliminated.

The IEEE IRPS continued to be organized through the 1970s and 1980s disseminating a plethora of knowledge on PoF. Several failure mechanisms and mathematical models were reported for a wide range of electronic components such as capacitors, semiconductors, resistors, and interconnects. In 1975, J.R. Black (1975) published his famous model for predicting electromigration time to failure, which continues to be valid even at the present time.

Metallization, metallurgical effects and bonding dominated the key presentations and papers published by IRPS. Some examples of key papers published included the *Agarwala* publication of experimental results for electromigration failures in thin-film conductors, the *Brodeur* (1975) description of high temperature operating life testing as a measure of processes used in fabrication of semiconductor wafers. *Macpherson, Day, Weisenberger and Christou* (1975) introduced the concept of fast temperature cycling as a key agent of failure in transistor metallization. It is worthwhile to note that PoF of non-silicon devices was first introduced in 1975 through six papers in the area of microwave and electro-optic devices. In addition, for the first time in 1975, the applications of accelerated testing were introduced as a method for obtaining PoF data on devices and components.

By 1983, CMOS PoF issues began to dominate the entire microelectronics industry and hence IRPS concentrated to a very large extent on sessions based on semiconductor instabilities, CMOS latch up analysis and MOS failure mechanisms. As current densities increased and device linewidths decreased electromigration became the key issue in the PoF of device structures. J.R. Lloyd (1983) presented the initial analysis of electromigration effects in multilevel geometries. The Time Dependent Breakdown phenomena was first reported in 1985 at IRPS, through the first developed physical model of TDDB by Chen, Holland and Hu (1985)

GaAs Device Reliability became an important part of the conference by 1983, and the paper by Dumas et al (1983) on long term degradation of GaAs Power Mesfets continues to be an important source of data to the present. Also reported was the first concern with single event effects in GaAs MESFETS, by Anderson et al (1983). It is worthy to note that in 1985, the first HEMT Reliability investigation results was reported by Christou et al (1985) at IRPS. High

Electron Transistors were the new devices which have since introduced a wide spectrum of new products such as GPS and mobile communications. The authors reported on the first observation of a diffusion controlled failure mechanism and also a susceptibility to alpha particle degradation.

Crook (1979) presented a model for time dependent dielectric breakdown of semiconductors as a function of operational and environmental conditions, as well as the device physical parameters. *Hieber and Pape* (1984) presented a creep-rupture equation that calculates time to rupture as a function of applied mechanical load and temperature. *Conrad, Mielnik, Musolino* (1988) presented a methodology to monitor and predict early life reliability failure mechanisms. The PoF investigations expanded rapidly and addressed new mechanisms such as the PoF of moisture related mechanisms, packaging and assembly as well as compound semiconductor devices. In 1979, *Vasofsky* published his seminal paper on water vapor sorption, followed by *Anderson, Christou and Sleger* (1979) on ionic-contamination-humidity effects. These were the first publications on the mechanism now known as MGRS (Migrative Resistive Shorts).

The 1990s also resulted in a major change in the assessment of the Pof F of microelectronics due to reduced failure rate requirements as well as the increased use of simulation to estimate reliability. The industry now sees the market pressures as drivers toward improvements in reliability. Reliability trends now parallel technology trends, and concepts of design-in reliability and total quality improvement prevail as reported by Chatterjee, Hunter, Amerasekera et al (1995). The end of the 1990s saw a new reliability challenge being addressed by the P of F community: The mechanisms related to new materials in a new millennium of Moore's law. The first investigations on MEMs reliability appeared, and the first experiments on failure

mechanisms of RF MEMs were reported at IRPS by Douglass (1998). This marked a departure for IRPS which previously emphasized P of F of devices and components from established manufacturing lines. The new approach for the reliability engineer is to work upstream, and identify failure mechanisms as early in the development cycle as possible.

By the late 1980s and early 1990s, several publications on PoF related research outside of the IEEE *Reliability Physics Symposium* also appeared. For example, *Pecht, Dasgupta, Barker, and Leonard* (1990) advocated use of PoF approach for reliability assessment as opposed to the part count technique. *Dasgupta and Pecht* (1991) presented material failure mechanism and damage models. *Engel* (1993) presented failure models for mechanical wear modes and mechanisms. *Modarres* (1993) distinguished between deterministic and probabilistic treatment of failures, and discussed probabilistic methods for quantifying and propagating uncertainties in physical models and engineering systems. *Cushing, Mortin, Stadterman and Malhotra* (1993) of US Army Materiel Systems Analysis Activity (AMSAA) Physics-of-Failure office, Aberdeen Proving Ground, Maryland compared empirically-based reliability prediction approaches (e.g., MIL-HDBK-217) with the PoF approach. They identified several limitations of using the MIL-HDBK-217, which could be addressed by using the PoF approach.

The 1990s also saw the publication of key radiation damage effects in microelectronics. The industry was now recognizing that cosmic ray effects inducing failure is a key issue in current and future generation of DRAMs. Cosmic rays as a significant source of soft errors in DRAMs and other devices was published as early as 1979. The work presented at IRPS showed clearly, for the first time that high energy neutrons produced by cosmic rays can be a major contributor to system soft error rate effects. In an elegant set of experiments, *McKee et al* (1996) was able

to measure the dependencies on cosmic ray neutron flux. During the 1990s, significant advances in characterization techniques were also important, as we see the convergence of characterization physics with complex mechanism analysis.

The 21st century has seen a new emphasis on technologies beyond CMOS. The demand for faster and lower power continues to grow and has put new pressure of refining the P of F approach. Development of SOI, and SOI related structures, as well as SiGe based bipolar transistors and passive RF elements has generated a new set of reliability problems which can only be solved through the P of F approach. The technological challenges have become formidable, but the new opportunity enabled by these technologies is now the new incentive driving reliability. The 21st century has thus seen the rapid development of statistical models to describe multiple failure such as the work of Fischer et al (2000) in the report on statistical models for bimodal electromigration failures. Other models have been reported by the researchers at the University of Maryland CALCE Center for Electronic Packaging. We now see the reporting of novel transistor findings such as those related to NBTI-induced interface states and hot carrier effects in novel gate dielectrics. The threshold voltage shift in p-FETs caused by negative bias temperature instability has emerged as one of the most serious reliability limitations of modern ULSI technology. This failure mechanism has become significant for newer technologies which operate at lower supply voltages (Stathis, LaRosa and Chou, 2004). Just as important however are the instabilities present with the new GaN HFET technologies due to interface traps as reported by Christou et al (2009).

Although several publications related to the PoF continued to be published through the 1990s and 2000s, a trend towards probabilistic consideration of PoF was also observed from the late

1990s. *Modarres, Kaminskiy, and Krivtsov* (1999) stated that prediction of failures is inherently a probabilistic problem due to uncertainties associated with failure-inducing agents that can result due to changes in environmental, operating, and use conditions; as well as uncertainties in PoF models and their parameters. The earliest effort in probabilistic consideration of PoF was by *Haggag, McMahon, Hess, Cheng, Lee and Lyding* (2000), who presented a probabilistic physics-of-failure (PPoF) approach to reliability assurance of high-performance chips by considering common defect activation energy distribution. *Hall and Strutt* (2003) presented PPoF models for component reliabilities by considering parameter and model uncertainties. *Azarkhail and Modarres* (2007) presented a Bayesian framework for uncertainty management in physics-based reliability models. *Matik and Sruk* (2008) highlighted the need for PoF to be probabilistic in order to consider variations of variables involved in processes contributing to the occurrence of failures. *Chamerlain, Chookah, and Modarres* (2009) presented a PPoF model for reliability assessment of gas cylinders, incorporating uncertainties associated with manufacturing process, material properties, and inspection methodology. *Chatterjee and Modarres* (2011) presented a PPoF approach for estimating steam generator tube rupture frequency considering the PoF and various uncertainties associated with environmental conditions, geometrical and material properties, PoF models, and model parameters.

Although the discussion on PoF has been presented chronologically in this article, an important milestone has been the publication of the PoF handbook for microelectronic systems in 2008 (*Salemi and Bernstein, 2008*). The handbook was the first of its kind that presented an approach for microelectronic system reliability assessment and qualification based on PoF. Another important activity currently underway is the development of a Web Accessible Repository of Physics-Based Models (WARP) under the aegis of the Reliability Information

Analysis Center (RIAC)². The objective of the WARP³ is to collect and analyze the characteristics of the PoF models for electronic, electromechanical and mechanical components in order to provide a centralized web-based repository accessible to researchers and engineers.

As we celebrate the fifty years of the PoF, RADC deserves a special gratitude including its chief and founder Joseph J. Naresky under whose leadership the PoF was first formally conceptualized and the symposium on “Physics of Failure in Electronics” organized in 1962 with considerable efforts by RADC’s Joseph Vaccaro. It is remarkable to see that many of the original ideas introduced in these symposia made the most significant impact on the understanding of failures in electronics and offered enduring models to estimate life characteristics. As was observed for the first time in the 1962 symposium, the PoF approach encompasses multiple disciplines such as reliability engineering, physics, metallurgy, and mathematical statistics and probability. The symposia of the 1960s provided PoF approaches for non-destructive test methods and for improving and predicting component reliability with limited resort to mass test data. While PoF analysis is complex, costly to apply, and limited for assessing the entire system; it provides the strongest characterization of reliability of components, structures and systems. The fact, that PoF as an approach for reliable product development has gained wide acceptance today in the commercial sector (e.g., Microsoft) as well as in several countries (e.g., Japan, Singapore, and Taiwan), is a tribute to its strong foundation established fifty years ago.

References:

Agarwala, B.N., “Electromigration failures in Au thin-film conductors”, *Proceedings of 13th Annual Reliability Physics Symposium*, pp: 107-112, 1975.

² <http://www.theriac.org>

³ The authors of this article, Chatterjee and Modarres are directly involved in the development of the WARP.

Anderson, W.T., Christou, A. and Sleger, K.J., “Ionic Contamination Effects on GaAs FETs”, *Proceedings of 17th Annual Proceedings in Reliability Physics*,” pp: 127-132, 1979.

Anderson,W.T., Binari, S.C., “Radiation Effects in GaAs Devices and ICs”, in *Proceedings of 21st Annual Proceedings of Reliability Physics*, pp:316-320, 1983.

Azarkhail, M., and Modarres, M., “A Novel Bayesian Framework for Uncertainty Management in Physics-Based Reliability Models”, *Proceedings of the ASME International Mechanical Engineering Congress and Exposition*, November 11-15, 2007, Seattle, WA.

Beau, J.F., “Management of the human element in the physics of failure”, *Proceedings of Third Annual Symposium on the Physics of Failure in Electronics*, pp: 264-279, 1964.

Black, J.R. “Physics of Electromigration”, *Proceedings of Twelfth Annual Symposium on the Physics of Failure in Electronics*”,pp: 142-149, 1974.

Bretts, G., Kozol, J., and Lampert, H., “Failure physics and accelerated testing”, *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 189-207, September, 1963.

Brodeur, J.E., “Process control by means of accelerated testing”, *Proceedings of 13th Annual Reliability Physics Symposium*, pp: 255-256, 1975.

Chamberlain, S., Chookah, M., and Modarres, M., “Development of a probabilistic mechanistic model for reliability assessment of gas cylinders in compressed natural gas vehicles,” *Journal of Risk and Reliability*, Vol. 223, Issue 4, pp: 289-299, 2009.

- Chatterjee, K.P., Hunter, W.R., Amerasekera, A., Aur, S., Duvvury, C., Nicollian, P.E., Ting, L.M., and Yang, P., "Trends for Deep Submicron VLSI and Their Implications for Reliability," in 33rd Annual Proceedings of IRPS, pp. 1-11, 1995.
- Chatterjee, K., and Modarres, M., "A probabilistic physics-of-failure approach to prediction of steam generator tube rupture frequency," *Proceedings of the International Topical Meeting on Probabilistic Safety Assessment and Analysis*, March 13-17, 2011, Wilmington, NC.
- Chen, I.C., Holland, S. and Hu, C., in 23rd Annual Proceedings of Reliability Physics, pp: 24-31, 1985.
- Christou, A. Tseng, W., Peckerar, M., Anderson, W.T., McCarthy, D.M., "Failure Mechanism Study of GaAs MODFET Devices and Integrated Circuits," 23rd Annual Proceedings of Reliability Physics, pp:54-59, 1985.
- Christou, A. and G. Paradee, "Strain Induced Buffer Layer Defects in GaN HFETs" in *Proceedings of 2009 IRPS*, pp: 718-722, 2009.
- Church, H.F., and Roberts, B.C., "Failure mechanisms of electronic components", *Proceedings of Fourth Annual Symposium on the Physics of Failure in Electronics*, pp: 156-178, 1965.
- Conrad, T.R., Mielnik, R.J., and Musolino, L.S., "A test methodology to monitor and predict early life reliability failure mechanisms", *Proceedings of 26th Annual Reliability Physics Symposium*, pp: 126-130, 1988.
- Crook, D.L., "Method of determining reliability screens for time dependent dielectric breakdown", *Proceedings of 17th Annual Reliability Physics Symposium*, pp: 1-7, 1979.

Cushing, M.J., Mortin, D.E., Stadterman, T.J., and Malhotra, A., "Comparison of Electronics-Reliability Assessment Approaches", *IEEE Transactions on Reliability*, Vol. 42, Issue 4, December 1993.

Dasgupta, A., and Pecht, M., "Material failure mechanisms and damage models", *IEEE Transactions on Reliability*, Vol. 40, Issue 5, pp: 531-536, December 1991.

Davis, H., "Introduction", *Proceedings of the First Annual Symposium on Physics of Failure in Electronics*, September 26-27, pp: 1-3, 1962.

Denson, W., "The history of reliability prediction", *IEEE Transactions on Reliability*, Vol. 47, Issue 3, pp: 321-328, September 1998.

Dodson, G.A., and Howard, B.T., "High stress aging to failure of semiconductor devices", *Proceedings of Seventh National Symposium on Reliability and Quality Control*, Philadelphia, PA, January 1961.

Douglass, M.R., "Lifetime Estimates and Unique Failure Mechanisms of the Digital Micromirror Device (DMD)," in 36th Annual IRPS Proceedings, pp: 9-16, 1998.

Dumas, J.M., Paugam, J., LeMouellic, C., and Boulaire, J.Y., "Long Term Degradation of GaAs Power MESFETs Induced By Surface Effects," 21st Annual Proceedings of Reliability Physics, pp: 226-229, 1983.

Earles, D.R., and Eddins, M.F., "Reliability physics (the physics of failure)", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 179-193, September 26-27, 1962.

Ebel, G.H., "Reliability physics in electronics: a historical view", *IEEE Transactions on Reliability*, Vol. 47, Issue 3, September 1998.

- Engel, P.A., "Failure models for mechanical wear modes and mechanisms", *IEEE Transactions on Reliability*, Vol. 42, Issue 2, June 1993.
- Epstein, B., "Statistical Aspects of Fracture Problems", *Journal of Applied Physics*, Vol. 19, February 1948.
- Frankel, H., and Kinsolving, W., "Reliability testing for hostile environments", *Proceedings of Eighth Annual Reliability Physics Symposium*, pp: 219, 1970.
- Fischer, A. H., etal, "Experimental Data and Statistical Models for Bimodal EM Failures", in 38th Annual Proceedings of IRPS, pp: 359-363, 2000.
- Gill, W., and Workman, W., "Reliability screening procedures for integrated circuits", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 101-140, 1966.
- Haggag, McMahon, Hess, Cheng, Lee, and Lyding, "A Probabilistic-Physics-of-Failure/Short-Time-Test Approach to Reliability Assurance for High-Performance Chips: Models for Deep-Submicron Transistors and Optical Interconnects", *Proceedings of IEEE Integrated Reliability Workshop*, pp: 179-182, October 23-26, 2000.
- Hall, P.L., and Strutt, J.E., "Probabilistic physics-of-failure models for component reliabilities using Monte Carlo simulation and Weibull analysis: a parametric study", *Reliability Engineering & System Safety*, Vol. 80, Issue 3, pp: 233-242, June 2003.
- Hieber, H., and Pape, K., "Lifetime of bonded contacts on thin film metallization", *Proceedings of 22nd Annual Reliability Physics Symposium*, pp: 128-133, 1984.
- Hollingshead, C.O., "A system oriented components selection optimization technique", *Proceedings of Eighth Annual Reliability Physics Symposium*, pp: 220-225, 1970.

Ingram, G.E., “Prediction of Device Reliability by Mechanisms-of-Failure Principles”, *Proceedings of Third Annual Symposium on the Physics of Failure in Electronics*, pp: 200-209, 1964.

Keen, R.S., Loewenstern, L.R., Schnable, G.L., “Mechanisms of Contact Failure in Semiconductor Devices”, *Proceedings of IEEE Sixth Annual Reliability Physics Symposium*, pp: 216-233, 1967.

Levinson, D.W., and Pohl, R.G., “Failure physics: an essential discipline for reliability engineering”, *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 108-122, September 26-27, 1962.

Lloyd, J.R., “Electromigration Induced Extrusions in Multilayer Technologies”, in 21st Annual Proceedings of Reliability Physics, : pp 208-211, 1983.

Matik, Z., and Sruck, V., “The Physics-of-Failure Approach in Reliability Engineering”, *Proceedings of IEEE International Conference on Information Technology Interfaces*, pp: 745-750, June 23-26, 2008.

MvKee et al, “Cosmic Ray Neutron Induced Upsets as a Major Contributor to the Soft Error Rate of Current and Future Generation DRAMs,” in 34th Annual Proceedings of IRPS, pp: 1-11, 1998.

Mclinn, J., “A short history of reliability”, *The Journal of the Reliability Information Analysis Center*, January 2011.

Macpherson, A.C., Day, H.M., Weisenberger, W.H., Christou, A., “13th Annual Proceedings, Reliability Physics”, pp:113-120, 1975.

- Miner, M.A., "Cumulative Damage in Fatigue", *Journal of Applied Mechanics*, Vol. 12, No. 3, pp: A- 159- 164, September, 1945.
- Modarres, M., "*What every engineer should know about reliability and risk analysis*", Marcel Dekker, New York, 1993.
- Modarres, M., Kaminskiy, M., and Krivtsov, V., "*Reliability engineering and risk analysis: A practical guide*", Marcel Dekker, New York, 1999.
- Naresky, J.J., "Foreword", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, September 26-27, 1962.
- Partridge, J., Hall, E.C., and Hanley, L.D., "The application of failure analysis in procuring and screening of integrated circuits", *Proceedings of Fourth Annual Symposium on the Physics of Failure in Electronics*, pp: 96-139, 1965.
- Payne, D.A., "Concerning the physics of failure of Barium Titanate capacitors", *Proceedings of IEEE Sixth Annual Symposium on Reliability Physics*, pp: 257-264, 1967.
- Pecht, M., Dasgupta, A., Barker, D., Leonard, C.T., "The reliability physics approach to failure prediction modeling", *Quality and Reliability Engineering International*, Vol. 6, Issue 4, pp: 267-273, September/October 1990.
- Potter, C.N., and Sawyer, D.E., "Optical scanning technique for semiconductor device screening and identification of surface and junction phenomena", *Proceedings of Fifth Annual Symposium on the Physics of Failure in Electronics*, pp: 37-50, 1966.
- Ryerson, C.M., "Project control to provide for the physics of failure in electronics", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 68-72, September 26-27, 1962.

- Ryerson, C.M., "Mathematical Modeling For Predicting Failure Rates Of Component Part", *Proceedings of IEEE Sixth Annual Reliability Physics Symposium*, pp: 10-15, 1967.
- Salemi, S., Yang, L., Dai, J., Qin, J., and Bernstein, J.B., "*Physics-of-Failure based handbook of microelectronic systems*", Reliability Information Analysis Center, Utica, NY, 2008.
- Schenck, J.F., "Progressive failure mechanisms of a commercial silicon diode", *Proceedings of Fifth Annual Symposium on the Physics of Failure in Electronics*, pp: 18-35, 1966.
- Schwuttke, G.H., "Yield problems in LSI technology", *Proceedings of Eighth Annual Reliability Physics Symposium*, pp: 274-280, 1970.
- Shiomi, H., "Cumulative degradation model and its application to component life estimation", *Proceedings of Fourth Annual Symposium on the Physics of Failure in Electronics*, pp: 74-94, 1965.
- Stathis, J.H., LaRosa, G., and A. Chou, "Broad Energy Distribution of NBTI induced Interface States in p MOSFETs with Ultra-Thin Nitrided Oxide," in 42nd Annual Proceedings of IRPS, PP: 1-10, 2004.
- Tamburrino, A.L., "Analysis of requirements in reliability physics", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 189-207, September, 1963.
- Thomas, R.E., "Some unifying concepts in reliability physics, mathematical models, and statistics", *Proceedings of Fifth Annual Symposium on the Physics of Failure in Electronics*, pp: 1-17, 1966.

Vaccaro, J., "Reliability and Physics of Failure Program at RADC", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 4-10, September 26-27, 1962.

Vasofsky, R.W., "Water Vapor Sorption by Package Sealants", *Proceedings of 17th Annual Proceedings on Reliability Physics*, pp: 91-96, 1979.

Weibull, W., "Statistical Evaluation of Data from Fatigue and Creep Rupture Tests, Part I: Fundamental Concepts and General Methods", Wright Air Development Center, Technical Report 59-400, Sweden, September 1959.

Weibull, W., "Fatigue Testing and Analysis of Results", *Pergamon Press*, London, 1961.

Workman, W., "Failure analysis techniques", *Proceedings of Third Annual Symposium on the Physics of Failure in Electronics*, pp: 238-263, 1964.

Zierdt, C.H., "Diagnostic techniques in semiconductor device stress response analysis", *Proceedings of First Annual Symposium on the Physics of Failure in Electronics*, pp: 91-97, September 26-27, 1962.

Since then, the physics-of-failure approach has dominated reliability modeling. In this approach, the root cause of an individual failure mechanism is studied and corrected to achieve some determined lifetime. Since wearout mechanisms are better understood, the goal of reliability engineers has been to design dominant mechanisms out of the useful life of the components by applying strict rules for every design feature. For instance, the learning \hat{C} E factor in the military handbook tries to take into consideration the effect of the number of years that the product has been in production. Therefore, the appropriate acceleration models are applied to the failure rates. Table 1.1 gives the temperature acceleration factor used in some of the traditional prediction procedures [2]. [Submitted on 10 Dec 2010]. Title:50 Years of Neutrino Physics. Authors:Marek Zralek. Download PDF. Abstract: Some important topics from history of neutrino physics over the last fifty years are discussed. History of neutrinos is older, at 4th December 2010 it will be eightieth anniversary of the "neutrino birth". In that day W. Pauli wrote the famous letter to participants of the physics conference at Tübingen with the suggestion that "there could exist in the nuclei electrically neutral particle". We will concentrate mostly on the 50 years of neutrino history just to show Physics-of-failure (PoF) approach is integral part of IRBE as in this approach reliability of the component and systems is predicted based on scientific models for identification of applicable failure mechanism and evaluation degradation to arrive at time to failure. The traditional statistical approach for reliability evaluation can predict the probability of failure but incapable of providing information on instant of failure. The physics-of-failure approach as part of prognostics framework can predict failure in advance with acceptable level of uncertainty. PoF as an approach is extensively The year 2012 marked the fiftieth anniversary of the physics of failure concept since it was first introduced in 1962 by the Rome Air Development Center (now known as the Air Force Research Laboratory). A chronological description of the important historical events that led to the birth and subsequent advancement of physics of failure concept over the last fifty years has been presented in this paper. Alongside, a review of physics of failure concepts and methodologies as they evolved in the last fifty years has also been provided. Discover the world's research. 17+ million members. Physics of failure and design for reliability can improve product performance throughout the development cycle. This DfR methodology served as the basis for the physics of failure (PoF) approach that is common in many industries today. What is Physics of Failure? PoF is a scientific discipline that determines the root causes of failure for electrical, electronic or electromechanical (EEE) items. These items can include: Piece parts. However, upcoming autonomous taxis are expected to operate 22 to 24 hours a day over 4 to 6 years. That means that the semiconductors and electronic modules powering these autonomous vehicles will be expected to operate 32,000 to 53,000 hours under conditions that exceed current industry expectations and validations requirements.